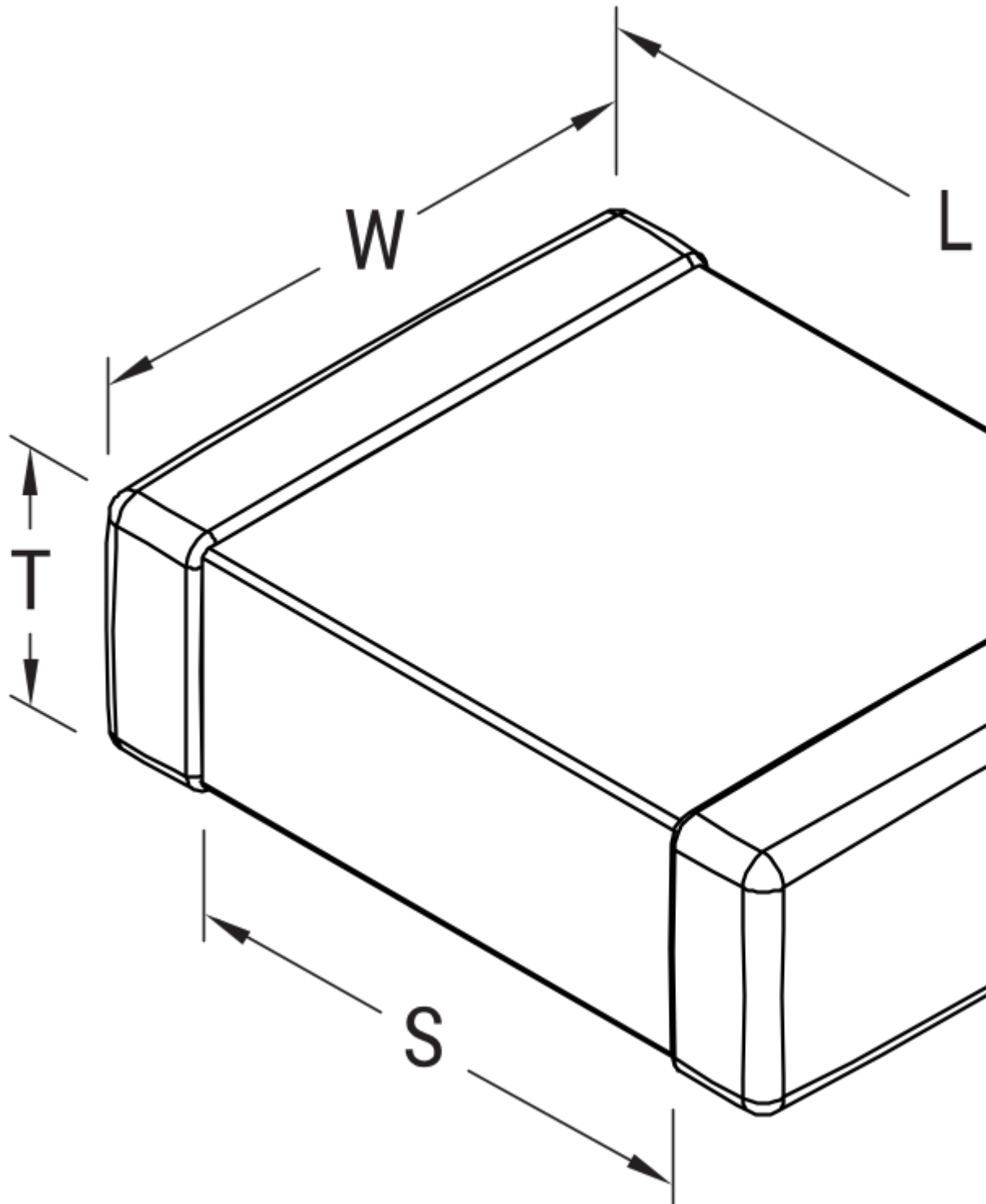


# C0402C152J3GECTU

## Aliases (C0402C152J3GEC7867)

ESD SMD Comm COG, Ceramic, 1500 pF, 5%, 25 VDC, COG, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I, 0402



Click [here](#) for the 3D model.

### Dimensions

Chip Size 0402

L 1mm +/-0.05mm

### Dimensions

W	0.5mm +/-0.05mm
T	0.5mm +/-0.05mm
S	0.3mm MIN
B	0.3mm +/-0.1mm

### Packaging Specifications

Packaging	T&R, 180mm, Paper Tape
Packaging Quantity	10000

### General Information

Series	ESD SMD Comm C0G
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I
Features	Temperature Stable, Low ESR, Class I
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Component Weight	1.06 mg
Shelf Life	78 Weeks
MSL	1

### Specifications

Capacitance	1500 pF
Measurement Condition	1 kHz 1.0Vrms
Capacitance Tolerance	5%
Voltage DC	25 VDC
ESD Level per AEC-Q200	6,000 V ESD Level
Dielectric Withstanding Voltage	62.5 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	C0G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	100 GOhms

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